

Future of Lightweighting Entry



Yanfeng Automotive Interiors

Compression Hybrid Molded Instrument Panel with Integrated Scoring

Compression Hybrid Molded Instrument Panels (CHyM) with Integrated Scoring is an exciting new innovation that YFAI has been developing. This new instrument panel carrier solves the need for reduced weight, lower cost, capital flexibility, and the use of renewable resources.

CHyM Instrument panels reduce mass by as much as 35% over traditional injection molded IPs. To create these parts, a light weight natural fiber mat is compression formed at the same time that structural features are injection molded onto the backside. Manufacturing costs are reduced and simplified by molding the airbag weakening line directly onto the back of the part. This eliminates the need for secondary scoring which is both process and cost intensive. Additionally, an alternate IP carrier design allows the airbag chute to be directly molded onto the back side for an integrated chute version. This not only further reduces costs but further reduces weight as well.

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